

#### 32Kx8 PowerStore nvSRAM

#### FEATURES

- 25, 45 ns Read Access & R/W Cycle Time
- Unlimited Read/Write Endurance
- Pin compatible with industry standard SRAMs
- Automatic Non-volatile STORE on Power Loss
- Automatic RECALL to SRAM on Power Up
- Non-Volatile STORE or RECALL under Software Control
- Unlimited RECALL Cycles
- 1 Million Store Cycles
- 100-Year Non-volatile Data Retention
- Single 5V <u>+</u>10% Power Supply
- Commercial and Industrial Temperatures
- 28-pin 300-mil and 330 mil SOIC Packages (RoHS-Compliant)

#### DESCRIPTION

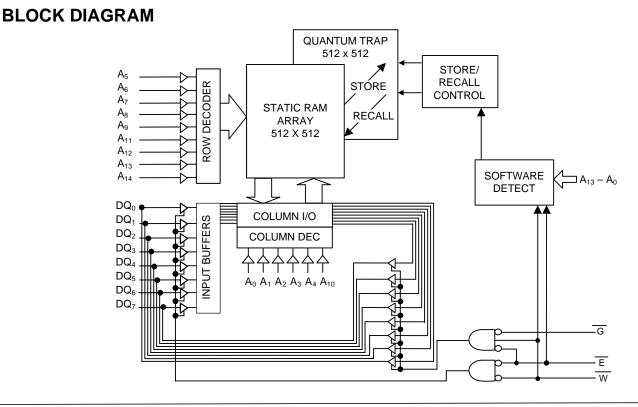
The Simtek STK15C88 is a 256Kb fast static RAM with a non-volatile Quantum Trap storage element included with each memory cell.

The SRAM provides the fast access & cycle times, ease of use and unlimited read & write endurance of a normal SRAM.

Data transfers automatically to the non-volatile storage cells when power loss is detected (the *STORE* operation). On power up, data is automatically restored to the SRAM (the *RECALL* operation). Both STORE and RECALL operations are also available under software control.

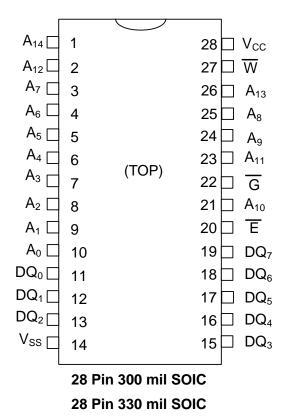
PowerStore nvSRAM products depend on the intrinsic system capacitance to maintain system power long enough for an automatic store on power loss. If the power ramp from 5 volts to 3.6 volts is faster than 10 ms, consider our 14C88 or 16C88 for more reliable operation.

The Simtek nvSRAM is the first monolithic non-volatile memory to offer unlimited writes and reads. It is the highest performance, most reliable non-volatile memory available.



This product conforms to specifications per the terms of Simtek standard warranty. The product has completed Simtek internal qualification testing and has reached production status.

#### **PIN CONFIGURATIONS**



#### **PIN DESCRIPTIONS**

Pin Name	I/O	Description
A <sub>14</sub> -A <sub>0</sub>	Input	Address: The 15 address inputs select one of 32,768 bytes in the nvSRAM array
DQ <sub>7</sub> -DQ <sub>0</sub>	I/O	Data: Bi-directional 8-bit data bus for accessing the nvSRAM
Ē	Input	Chip Enable: The active low $\overline{E}$ input selects the device
W	Input	Write Enable: The active low $\overline{W}$ enables data on the DQ pins to be written to the address location latched by the falling edge of $\overline{E}$
G	Input	Output Enable: The active low $\overline{G}$ input enables the data output buffers during read cycles. De-asserting $\overline{G}$ high caused the DQ pins to tri-state.
V <sub>CC</sub>	Power Supply	Power: 5.0V, <u>+</u> 10%
V <sub>SS</sub>	Power Supply	Ground

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### **ABSOLUTE MAXIMUM RATINGS**<sup>a</sup>

Voltage on Input Relative to Ground	
Voltage on Input Relative to $V_{SS} \dots \dots \dots -0.6V$ to $(V_{CC} + 0.5V)$	
Voltage on DQ <sub>0-7</sub> 0.5V to (V <sub>CC</sub> + 0.5V)	
Temperature under Bias	
Storage Temperature65°C to 150°C	
Power Dissipation	
DC Output Current (1 output at a time, 1s duration)	

### **DC CHARACTERISTICS**

N	ote	a:	

e a: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

#### (V<sub>CC</sub> = 5.0V $\pm$ 10%)

CYMPOL		COMMERCIAL		INDUSTRIAL			NOTES	
SYMBOL	PARAMETER	MIN	MIN MAX I		MAX	UNITS	NOTES	
I <sub>CC1</sub> b	Average V <sub>CC</sub> Current		97 70		100 70	mA mA	t <sub>AVAV</sub> = 25ns t <sub>AVAV</sub> = 45ns	
I <sub>CC2</sub> c	Average V <sub>CC</sub> Current during STORE		3		3	mA	All Inputs Don't Care, V <sub>CC</sub> = max	
I <sub>CC3</sub> b	Average V <sub>CC</sub> Current at t <sub>AVAV</sub> = 200ns 5V, 25°C, Typical		10		10	mA	$\overline{W} \ge (V_{CC} - 0.2V)$ All Others Cycling, CMOS Levels	
I <sub>CC4</sub> c	Average V <sub>CAP</sub> Current during AutoStore Cycle		2		2	mA	All Inputs Don't Care	
I <sub>SB1</sub> <sup>d</sup>	Average V <sub>CC</sub> Current (Standby, Cycling TTL Input Levels)		30 22		31 23	mA mA	$\begin{array}{l} t_{\text{AVAV}} = 25 \text{ns}, \ \overline{E} \geq V_{\text{IH}} \\ t_{\text{AVAV}} = 45 \text{ns}, \ \overline{E} \geq V_{\text{IH}} \end{array}$	
I <sub>SB2</sub> <sup>d</sup>	V <sub>CC</sub> Standby Current (Standby, Stable CMOS Input Levels)		1.5		1.5	mA	$\label{eq:constraint} \begin{split} \overline{E} &\geq (V_{CC} - 0.2V) \\ \text{All Others } V_{IN} &\leq 0.2V \text{ or } \geq (V_{CC} - 0.2V) \end{split}$	
I <sub>ILK</sub>	Input Leakage Current		±1		±1	μA	$V_{CC} = max$ $V_{IN} = V_{SS}$ to $V_{CC}$	
I <sub>OLK</sub>	Off-State Output Leakage Current		±5		±5	μA	$\begin{array}{l} V_{CC} = max \\ V_{IN} = V_{SS} \text{ to } V_{CC}, \ \overline{E} \text{ or } \overline{G} \geq V_{IH} \end{array}$	
VIH	Input Logic "1" Voltage	2.2	V <sub>CC</sub> + .5	2.2	V <sub>CC</sub> + .5	V	All Inputs	
V <sub>IL</sub>	Input Logic "0" Voltage	V <sub>SS</sub> – .5	0.8	V <sub>SS</sub> – .5	0.8	V	All Inputs	
V <sub>OH</sub>	Output Logic "1" Voltage	2.4		2.4		V	I <sub>OUT</sub> =-4mA	
V <sub>OL</sub>	Output Logic "0" Voltage		0.4		0.4	V	I <sub>OUT</sub> = 8mA	
T <sub>A</sub>	Operating Temperature	0	70	-40	85	°C		

Note b:  $I_{CC_1}$  and  $I_{CC_3}$  are dependent on output loading and cycle rate. The specified values are obtained with outputs unloaded.

Note c:  $I_{CC_2}$  and  $I_{CC_4}$  are the average currents required for the duration of the respective *STORE* cycles (t<sub>STORE</sub>). Note d:  $\overline{E} \ge V_{IH}$  will not produce standby current levels until any nonvolatile cycle in progress has timed out.

### AC TEST CONDITIONS

Input Pulse Levels 0V to 3V
Input Rise and Fall Times
Input and Output Timing Reference Levels 1.5V
Output Load

### **CAPACITANCE**<sup>e</sup> ( $T_A = 25^{\circ}C, f = 1.0MHz$ )

SYMBOL	PARAMETER	MAX	UNITS	CONDITIONS
C <sub>IN</sub>	Input Capacitance	5	pF	$\Delta V = 0$ to 3V
C <sub>OUT</sub>	Output Capacitance	7	pF	$\Delta V = 0$ to 3V

Note e: These parameters are guaranteed but not tested.

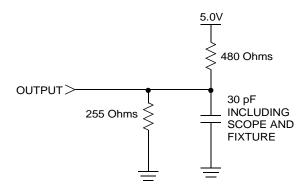


Figure 1: AC Output Loading



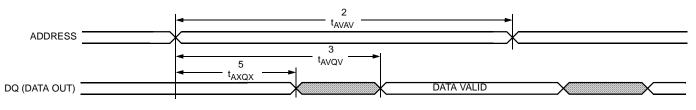
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### SRAM READ CYCLES #1 & #2 (V<sub>CC</sub> = $5.0V \pm 10\%$ )

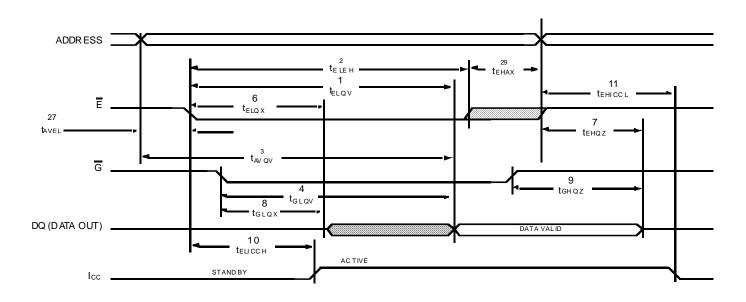
	SYMBOLS			STK15	STK15C88-25		C88-45	UNITS
NO.	#1, #2	Alt.	PARAMETER		MAX	MIN	MAX	UNITS
1	t <sub>ELQV</sub>	t <sub>ACS</sub>	Chip Enable Access Time		25		45	ns
2	t <sub>AVAV</sub> <sup>f</sup> , t <sub>ELEH</sub> <sup>f</sup>	t <sub>RC</sub>	Read Cycle Time	25		45		ns
3	t <sub>AVQV</sub> g	t <sub>AA</sub>	Address Access Time		25		45	ns
4	t <sub>GLQV</sub>	t <sub>OE</sub>	Output Enable to Data Valid		10		20	ns
5	t <sub>AXQX</sub> g	t <sub>OH</sub>	Output Hold after Address Change	5		5		ns
6	t <sub>ELQX</sub>	t <sub>LZ</sub>	Address Change or Chip Enable to Output Active	5		5		ns
7	t <sub>EHQZ</sub> h	t <sub>HZ</sub>	Address Change or Chip Disable to Output Inactive		10		15	ns
8	t <sub>GLQX</sub>	tolz	Output Enable to Output Active	0		0		ns
9	t <sub>GHQZ</sub> h	t <sub>OHZ</sub>	Output Disable to Output Inactive		10		15	ns
10	t <sub>ELICCH</sub> e	t <sub>PA</sub>	Chip Enable to Power Active			0		ns
11	t <sub>EHICCL</sub> d, e	t <sub>PS</sub>	Chip Disable to Power Standby		25		45	ns

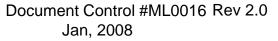
Note f:  $\overline{W}$  must be high during SRAM READ cycles and low during SRAM WRITE cycles. Note g: I/O state assumes  $\overline{E}$ ,  $\overline{G} \leq V_{IL}$  and  $\overline{W} \geq V_{IH}$ ; device is continuously selected. Note h: Measured  $\pm$  200mV from steady state output voltage.

### SRAM READ CYCLE #1: Address Controlled<sup>f, g</sup>



### SRAM READ CYCLE #2: E and G Controlled<sup>f</sup>







### STK15C88

#### SRAM WRITE CYCLES #1 & #2

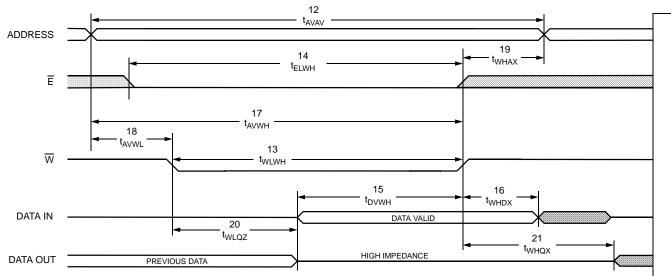
(V<sub>CC</sub> = 5.0V  $\pm$  10%)

	SYMBOLS				STK15C88-25		STK15C88-45		
NO.	#1	#2	Alt.	PARAMETER	MIN	MAX	MIN	MAX	UNITS
12	t <sub>AVAV</sub>	t <sub>AVAV</sub>	t <sub>WC</sub>	Write Cycle Time	25		45		ns
13	t <sub>WLWH</sub>	t <sub>WLEH</sub>	t <sub>WP</sub>	Write Pulse Width	20		30		ns
14	t <sub>ELWH</sub>	t <sub>ELEH</sub>	t <sub>CW</sub>	Chip Enable to End of Write	20		30		ns
15	t <sub>DVWH</sub>	t <sub>DVEH</sub>	t <sub>DW</sub>	Data Set-up to End of Write	10		15		ns
16	t <sub>WHDX</sub>	t <sub>EHDX</sub>	t <sub>DH</sub>	Data Hold after End of Write	0		0		ns
17	t <sub>AVWH</sub>	t <sub>AVEH</sub>	t <sub>AW</sub>	Address Set-up to End of Write	20		30		ns
18	t <sub>AVWL</sub>	t <sub>AVEL</sub>	t <sub>AS</sub>	Address Set-up to Start of Write	0		0		ns
19	t <sub>WHAX</sub>	t <sub>EHAX</sub>	t <sub>WR</sub>	Address Hold after End of Write	0		0		ns
20	t <sub>WLQZ</sub> h, i		t <sub>WZ</sub>	Write Enable to Output Disable		10		15	ns
21	t <sub>WHQX</sub>		t <sub>OW</sub>	Output Active after End of Write	5		5		ns

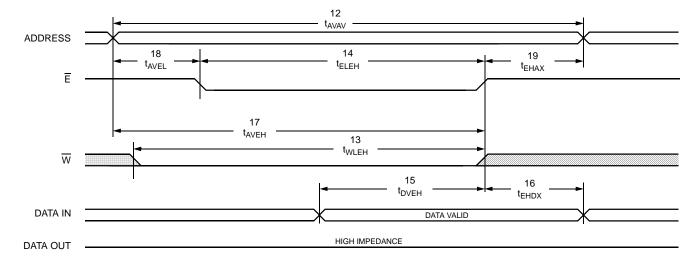
Note i: If  $\overline{W}$  is low when  $\overline{E}$  goes low, the outputs remain in the high-impedance state.

Note j:  $\overline{E}$  or  $\overline{W}$  must be  $\ge V_{IH}$  during address transitions.

### SRAM WRITE CYCLE #1: W Controlled<sup>j</sup>



### SRAM WRITE CYCLE #2: E Controlled



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## <u>STK15C88</u>

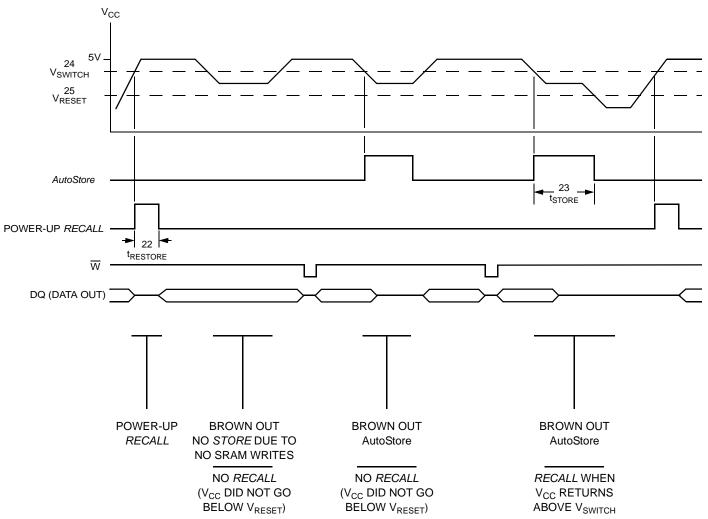
#### $(V_{CC} = 5.0V \pm 10\%)$

NO.	SYMBOLS	PARAMETER		5C88		NOTES
	Standard			MAX	UNITS	
22	<sup>t</sup> RESTORE	Power-up RECALL Duration		550	μs	k
23	<sup>t</sup> STORE	STORE Cycle Duration		10	ms	g
24	V <sub>SWITCH</sub>	Low Voltage Trigger Level	4.0	4.5	V	
25	V <sub>RESET</sub>	Low Voltage Reset Level		3.6	V	

Note k:  $t_{\text{RESTORE}}$  starts from the time V<sub>CC</sub> rises above V<sub>SWITCH</sub>.



AutoStore™/POWER-UP RECALL



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#### SOFTWARE STORE/RECALL MODE SELECTION

Ē	w	A <sub>13</sub> - A <sub>0</sub> (hex)	MODE	I/O	NOTES
L	Н	0E38 31C7 03E0 3C1F 303F 0FC0	Read SRAM Read SRAM Read SRAM Read SRAM Read SRAM Nonvolatile <i>STORE</i>	Output Data Output Data Output Data Output Data Output Data Output High Z	l, m
L	н	0E38 31C7 03E0 3C1F 303F 0C63	Read SRAM Read SRAM Read SRAM Read SRAM Read SRAM Nonvolatile <i>RECALL</i>	Output Data Output Data Output Data Output Data Output Data Output High Z	l, m

Note I: The six consecutive addresses must be in the order listed. W must be high during all six consecutive E controlled cycles to enable a nonvolatile cycle.

Note m: While there are 15 addresses on the STK15C88, only the lower 14 are used to control software modes.

#### SOFTWARE STORE/RECALL CYCLE<sup>n, o</sup>

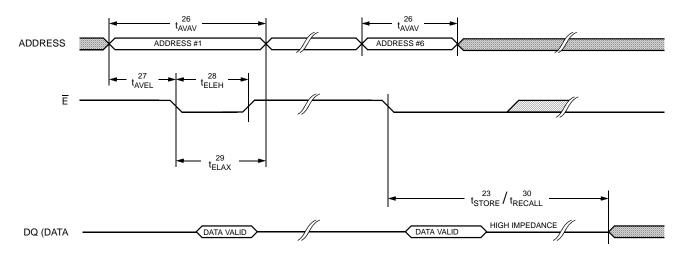
#### (V<sub>CC</sub> = 5.0V $\pm$ 10%)

	SYMBOLS	DADAMETED	STK15	C88-25	STK15		
NO.		PARAMETER		MAX	MIN	MAX	UNITS
26	t <sub>AVAV</sub>	STORE/RECALL Initiation Cycle Time	25		45		ns
27	t <sub>AVEL</sub> n	Address Set-up Time	0		0		ns
28	t <sub>ELEH</sub> n	Clock Pulse Width	20		30		ns
29	t <sub>ELAX</sub> <sup>g, n</sup>	Address Hold Time	20		20		ns
30	t <sub>RECALL</sub>	RECALL Duration		20		20	μs

Note n: The software sequence is clocked on the falling edge of  $\overline{E}$  controlled READs without involving G (double clocking will abort the sequence). See application note: MA0002 http://www.simtek.com/attachments/AppNote02.pdf.

Note o: The six consecutive addresses must be in the order listed in the Software *STORE/RECALL* Mode Selection Table: (0E38, 31C7, 03E0, 3C1F, 303F, 0FC0) for a *STORE* cycle or (0E38, 31C7, 03E0, 3C1F, 303F, 0C63) for a *RECALL* cycle. W must be high during all six consecutive cycles.

### SOFTWARE STORE/RECALL CYCLE: E Controlled<sup>o</sup>





## **nvSRAM OPERATION**

The STK15C88 is a versatile memory chip that provides several modes of operation. The STK15C88 can operate as a standard  $32K \times 8$  SRAM. It has a  $32K \times 8$  nonvolatile element shadow to which the SRAM information can be copied, or from which the SRAM can be updated in nonvolatile mode.

#### NOISE CONSIDERATIONS

Note that the STK15C88 is a high-speed memory and so must have a high-frequency bypass capacitor of approximately  $0.1\mu$ F connected between V<sub>CC</sub> and V<sub>SS</sub>, using leads and traces that are as short as possible. As with all high-speed CMOS ICs, normal careful routing of power, ground and signals will help prevent noise problems.

#### SRAM READ

The <u>STK15C88</u> performs a READ cycle whenever  $\overline{E}$  and  $\overline{G}$  are low and  $\overline{W}$  is high. The address specified on pins A<sub>0-14</sub> determines which of the 32,768 data bytes will be accessed. When the READ is initiated by an address transition, the outputs will be valid after a delay of t<sub>AVQV</sub> (READ cycle #1). If the READ is initiated by  $\overline{E}$  or  $\overline{G}$ , the outputs will be valid at t<sub>ELQV</sub> or at t<sub>GLQV</sub>, whichever is later (READ cycle #2). The data outputs will repeatedly respond to address changes within the t<sub>AVQV</sub> access time without the need for transitions on any control input pins, and will remain valid until another address change or until  $\overline{E}$  or  $\overline{G}$  is brought high.

#### **SRAM WRITE**

A WRITE cycle is performed whenever  $\overline{E}$  and  $\overline{W}$  are low. The address inputs must be stable prior to entering the WRITE cycle and must remain stable until either  $\overline{E}$  or  $\overline{W}$  goes high at the end of the cycle. The data on the common I/O pins DQ<sub>0-7</sub> will be written into the memory if it is valid t<sub>DVWH</sub> before the end of a  $\overline{W}$  controlled WRITE or t<sub>DVEH</sub> before the end of an  $\overline{E}$  controlled WRITE.

It is recommended that  $\overline{G}$  be kept high during the entire WRITE cycle to avoid data bus contention on the common I/O lines. If  $\overline{G}$  is left low, internal circuitry will turn off the output buffers  $t_{WLQZ}$  after  $\overline{W}$  goes low.

#### SOFTWARE NONVOLATILE STORE

The STK15C88 software *STORE* cycle is initiated by executing sequential READ cycles from six specific address locations. During the *STORE* cycle an erase of the previous nonvolatile data is first performed, followed by a program of the nonvolatile elements. The program operation copies the SRAM data into nonvolatile memory. Once a *STORE* cycle is initiated, further input and output are disabled until the cycle is completed.

Because a sequence of READs from specific addresses is used for *STORE* initiation, it is important that no other READ or WRITE accesses intervene in the sequence or the sequence will be aborted and no *STORE* or *RECALL* will take place.

To initiate the software *STORE* cycle, the following READ sequence must be performed:

1. Read address	0E38 (hex)	Valid READ
2. Read address	31C7 (hex)	Valid READ
3. Read address	03E0 (hex)	Valid READ
4. Read address	3C1F (hex)	Valid READ
5. Read address	303F (hex)	Valid READ
6. Read address	0FC0 (hex)	Initiate STORE cycle

The software sequence must be clocked with  $\overline{E}$  controlled READs.

Once the sixth address in the sequence has been entered, the *STORE* cycle will commence and the chip will be disabled. It is important that READ cycles and not WRITE cycles be used in the sequence, although it is not necessary that  $\overline{G}$  be low for the sequence to be valid. After the  $t_{\text{STORE}}$  cycle time has been fulfilled, the SRAM will again be activated for READ and WRITE operation.

#### SOFTWARE NONVOLATILE RECALL

A software *RECALL* cycle is initiated with a sequence of READ operations in a manner similar to the software *STORE* initiation. To initiate the *RECALL* cycle, the following sequence of READ operations must be performed:

1.	Read address	0E38 (hex)	Valid READ
2.	Read address	31C7 (hex)	Valid READ
3.	Read address	03E0 (hex)	Valid READ
4.	Read address	3C1F (hex)	Valid READ
5.	Read address	303F (hex)	Valid READ
6.	Read address	0C63 (hex)	Initiate RECALL cycle



Internally, *RECALL* is a two-step procedure. First, the SRAM data is cleared, and second, the nonvolatile information is transferred into the SRAM cells. After the  $t_{RECALL}$  cycle time the SRAM will once again be ready for READ and WRITE operations. The *RECALL* operation in no way alters the data in the nonvolatile elements. The nonvolatile data can be recalled an unlimited number of times.

### *AutoStore*<sup>™</sup> OPERATION

The STK15C88 uses the intrinsic system capacitance to perform an automatic *STORE* on power down. As long as the system power supply takes at least  $t_{\text{STORE}}$  to decay from  $V_{\text{SWITCH}}$  down to 3.6V, the STK15C88 will safely and automatically store the SRAM data in nonvolatile elements on power down.

In order to prevent unneeded *STORE* operations, automatic *STORE*s will be ignored unless at least one WRITE operation has taken place since the most recent *STORE* or *RECALL* cycle. Software-initiated *STORE* cycles are performed regardless of whether a WRITE operation has taken place. Additional information may be found in applications note "Applying the STK11C88, STK15C88 and STK16C88 32K nvSRAM."

#### POWER-UP RECALL

100

80

60

40

20

0

Average Active Current (mA)

During power up, or after any low-power condition ( $V_{CC} < V_{RESET}$ ), an internal *RECALL* request will be latched. When  $V_{CC}$  once again exceeds the sense voltage of  $V_{SWITCH}$ , a *RECALL* cycle will automatically be initiated and will take  $t_{RESTORE}$  to complete.

If the STK15C88 is in a WRITE state at the end of power-up *RECALL*, the SRAM data will be corrupted.

TTL

CMOS

200

150

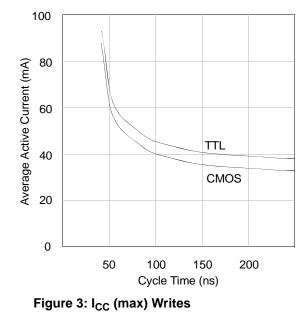
To help avoid this situation, a 10K Ohm resistor should be connected either between  $\overline{W}$  and system V<sub>cc</sub> or between  $\overline{E}$  and system V<sub>cc</sub>.

#### HARDWARE PROTECT

The STK15C88 offers hardware protection against inadvertent *STORE* operation and SRAM WRITES during low-voltage conditions. When  $V_{CC} < V_{SWITCH}$ , all software *STORE* operations and SRAM WRITES are inhibited.

#### LOW AVERAGE ACTIVE POWER

The STK15C88 draws significantly less current when it is cycled at times longer than 50ns. Figure 2 shows the relationship between  $I_{cc}$  and READ cycle time. Worst-case current consumption is shown for both CMOS and TTL input levels (commercial temperature range,  $V_{cc} = 5.5V$ , 100% duty cycle on chip enable). Figure 3 shows the same relationship for WRITE cycles. If the chip enable duty cycle is less than 100%, only standby current is drawn when the chip is disabled. The overall average current drawn by the STK15C88 depends on the following items: 1) CMOS vs. TTL input levels; 2) the duty cycle of chip enable; 3) the overall cycle rate for accesses; 4) the ratio of READs to WRITEs; 5) the operating temperature; 6) the  $V_{cc}$  level; and 7) I/O loading.



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50

100

Cycle Time (ns) Figure 2: I<sub>CC</sub> (max) Reads





#### **BEST PRACTICES**

nvSRAM products have been used effectively for over 15 years. While ease-of-use is one of the product's main system values, experience gained working with hundreds of applications has resulted in the following suggestions as best practices:

 The non-volatile cells in an nvSRAM are programmed on the test floor during final test and quality assurance. Incoming inspection routines at customer or contract manufacturer's sites will sometimes reprogram these values. Final NV patterns are typically repeating patterns of AA, 55, 00, FF, A5, or 5A. End product's firmware should not assume an NV array is in a set programmed state. Routines that check memory content values to determine first time system configuration, cold or warm boot status, etc. should always program a unique NV pattern (e.g., complex 4-byte pattern of 46 E6 49 53 hex or more random bytes) as part of the final system manufacturing test to ensure these system routines work consistently.

• Power up boot firmware routines should rewrite the nvSRAM into the desired state. While the nvSRAM is shipped in a preset state, best practice is to again rewrite the nvSRAM into the desired state as a safeguard against events that might flip the bit inadvertently (program bugs, incoming inspection routines, etc.).





# **ORDERING INFORMATION** STK15C88 - N F 45 I TR **Packaging Options** Blank = Tube TR = Tape and Reel **Temperature Range** Blank = Commercial (0 to $70^{\circ}$ C) $I = Industrial (-40 to 85^{\circ}C)$ Access Time 25 = 25ns 45 = 45ns Lead Finish F = 100% Sn (Matte Tin) Package S = Plastic 28-pin 330 mil SOIC

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N = Plastic 28-pin 300 mil SOIC

## STK15C88

### **ORDERING CODES**

Part Number				
STK15C88-SF25				
STK15C88-SF45				
STK15C88-NF25				
STK15C88-NF45				
STK15C88-SF25TR				
STK15C88-SF45TR				
STK15C88-NF25TR				
STK15C88-NF45TR				
STK15C88-SF25I				
STK15C88-SF45I				
STK15C88-NF25I				
STK15C88-NF45I				
STK15C88-SF25ITR				
STK15C88-SF45ITR				
STK15C88-NF25ITR				
STK15C88-NF45ITR				

#### Description

5V 32Kx8 PowerStore nvSRAM SOP28-330 5V 32Kx8 PowerStore nvSRAM SOP28-330 5V 32Kx8 PowerStore nvSRAM SOP28-300 5V 32Kx8 PowerStore nvSRAM SOP28-300 5V 32Kx8 PowerStore nvSRAM SOP28-330 5V 32Kx8 PowerStore nvSRAM SOP28-330 5V 32Kx8 PowerStore nvSRAM SOP28-300 5V 32Kx8 PowerStore nvSRAM SOP28-300 5V 32Kx8 PowerStore nvSRAM SOP28-330 5V 32Kx8 PowerStore nvSRAM SOP28-330 5V 32Kx8 PowerStore nvSRAM SOP28-300 5V 32Kx8 PowerStore nvSRAM SOP28-300 5V 32Kx8 PowerStore nvSRAM SOP28-330 5V 32Kx8 PowerStore nvSRAM SOP28-330 5V 32Kx8 PowerStore nvSRAM SOP28-300 5V 32Kx8 PowerStore nvSRAM SOP28-300

#### **Access Times**

25 ns access time 45 ns access time 25 ns access time 45 ns access time

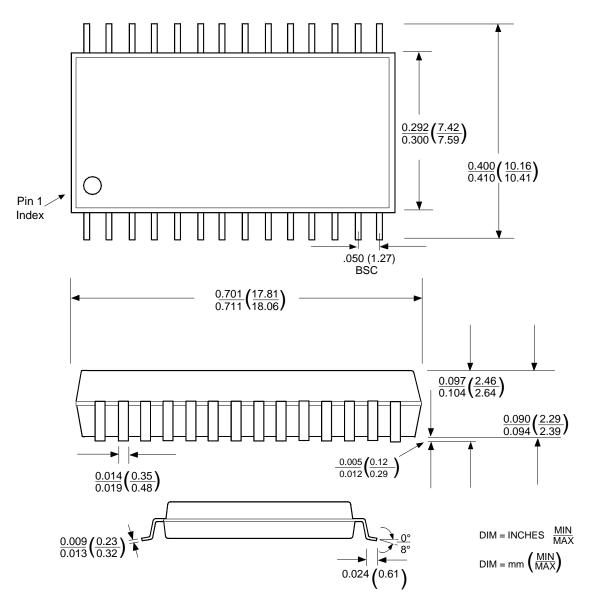
#### Temperature

Commercial Commercial Commercial Commercial Commercial Commercial Commercial Commercial Industrial Industrial Industrial Industrial Industrial Industrial Industrial Industrial



## **PACKAGE DRAWINGS**

### 28 Pin 300 mil SOIC

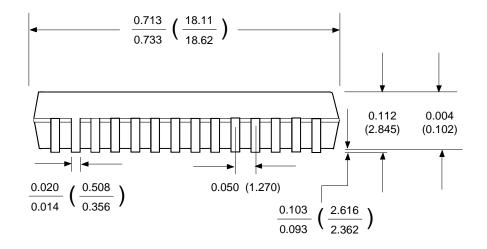


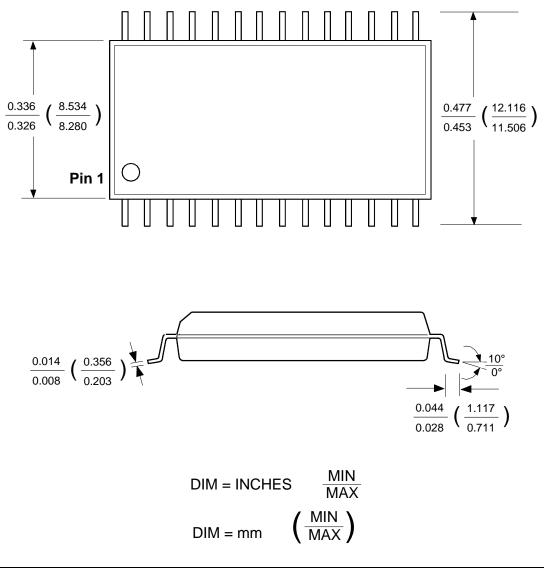


Document Control #ML0016 Rev 2.0 Jan, 2008

## STK15C88

### 28 Pin 330 mil SOIC







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Document Control #ML0016 Rev 2.0

#### **Document Revision History**

Revision	Date	Summary	
0.0	December 2002		
0.1	September 2003	Added lead-free lead finish	
0.2	March 2006	Removed DIP packages, Removed 35ns Speed Grade, Remove leaded lead finish	
0.3	February 2007	Add fast power-down slew rate information Add Tape Reel Ordering Options Add Product Ordering Code Listing Add Package Drawings Reformat Entire Document	
0.4	July 2007	extend definition of t <sub>HZ</sub> (#7) update fig. SRAM READ CYCLE #2, SRAM WRITE CYCLE #1, Note I and Note n to clarify product usage	
2.0	January 2008	Page 4: in SRAM Read Cycles #1 & #2 table, revised description for t <sub>ELQX</sub> and t <sub>EHQZ</sub> and changed Symbol #2 to t <sub>ELEH</sub> for Read Cycle Time; updated SRAM Read Cycle #2 timing diagram and changed title to add G controlled. Page 10: added best practices section. Page 12: added access times column to the Ordering codes.	

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